



SALES BULLETIN

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To: Atmel Worldwide Sales, Representatives and Distributors

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MODIFICATION OF PCN AT25F512

This is an updated modification to the earlier PCN# SC040401A that was released in March 2004, for the AT25F512 die shrink.

Description of Change:

*Die size reduction of the AT25F512 in the Industrial Temperature (-40 to 85C). The new version device will be manufactured utilizing the 39k (.25u) process versus the 37k (.35u) process for the current AT25F512. The 39k process is a fully stable and mature process. There has been a change in the way we offer the shrink version, a NEW part number will be created by adding an "A" to the suffix of the part identifier for the shrink: AT25F512A. The AT25F512A is pin to pin compatible with the current SPI FLASH 512K, AT25F512 devices. To improve programming time, the new shrink will have 2 sectors of 128 bytes per page compared to 256 bytes pages per sector in the previous version. **There has been a change in the returned value of the Product Identification (RDID) command, the AT25F512A RDID code is 65h compared to 60h from the AT25F512 product.** In addition, to accommodate the growing movement to Lead-Free products, the new shrink will ONLY be available in Lead-Free / Halogen-Free, which is backwards compatible with standard leaded production.*

Please help to inform your customers accordingly.

Thank you.